

NEWS RELEASE

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New Product

Thermal profiling solutions vendor SolderStar extends range to include Vapour Phase solder support

This newly developed system features a unique design to allow profiling of vapour phase soldering processes. The system is usable in both batch and inline machines, including those with vacuum stages.

The sealed thermal barrier comprises a lightweight outer skin coated with PTFE to minimise energy absorption from the vapour, yet achieves two times the performance of a standard reflow system. A small form factor datalogger is installed inside the shield to capture profile information from the circuit board being processed; information can also be relayed in real-time to the user via a 2.4GHz telemetry link.

For the quick preparation of a test, thermocouple connectors are fitted to the outside of the barrier. After each run through the machine, the barrier can be opened and the datalogger easily removed; this approach provides faster cool down cycles and reduced possibility of damage to the datalogger unit.

The software supplied with the system has additional support for definition of the vapour phase process allowing engineer to quickly establish the optimum settings for a given assembly.

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About SolderStar

SolderStar is a specialist in the design, development and manufacture of thermal profiling equipment for the electronics industry. SolderStar's range of instruments and software tools offers leading-edge performance, functionality, heat-resistance and miniaturisation.

SolderStar satisfies all of today's thermal process control needs, from full-feature high performance product profiling for reflow, wave and vapour phase solder processes, to fully integrated SPC capabilities for continuous quality and process control.

For more information about SolderStar, visit the company's website at www.solderstar.co.uk.

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